

Structure fabrication for CLIC

CLIC08,

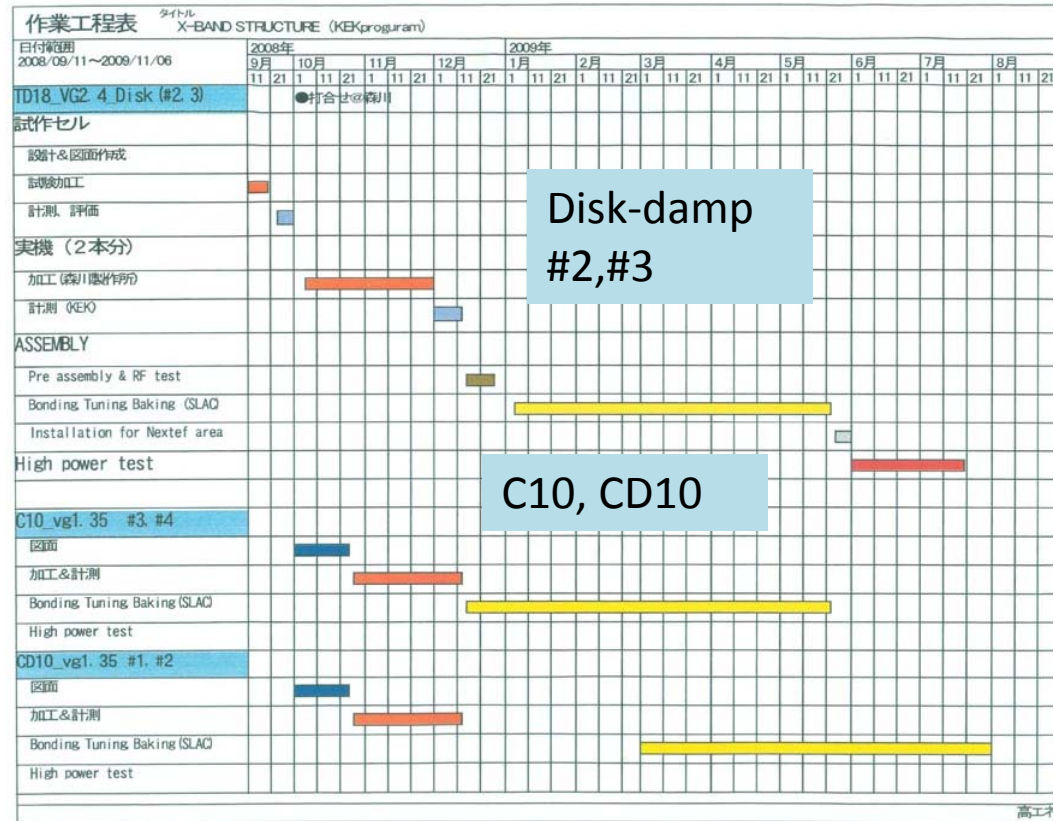
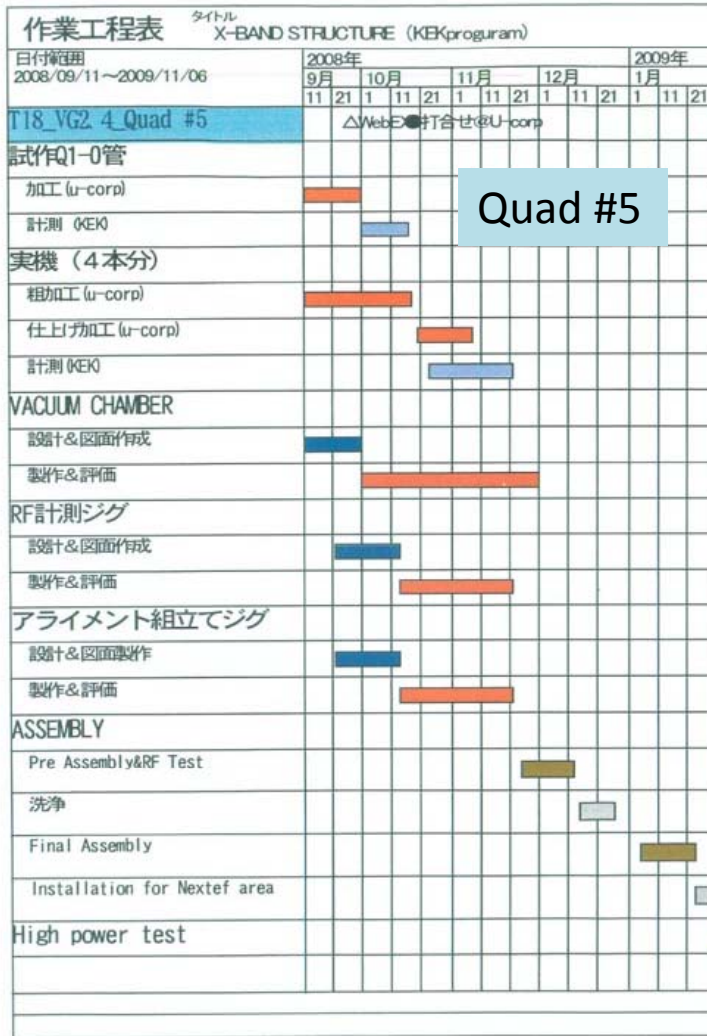
Oct. 14-17, 2008

KEK, T. Higo

Strategy of structure fabrication at KEK

- Re-establish GLC/NLC structure fab technique
 - 60-100MV/m
- Extend it to heavily damped structure for CLIC
 - Disk damp confirmation
- Learn about fabrication by all milling
 - Study high gradient performance
 - Study mass production feasibility
- Discuss about the practical candidate
 - For near future application in a few years

Structure fabrication plan



Disk-damp fabrication

- Started with technology of T18_VG2.4_Disk
 - Material
 - OFC
 - Machining
 - Usual turning for disk
 - Usual milling for coupler of mode converter type
 - Surface treatments
 - SLAC does all
 - CP, DB and VAC baking
- Take the same method but with milling in each cell
 - Mechanical design by KEK
 - Fabrication study done

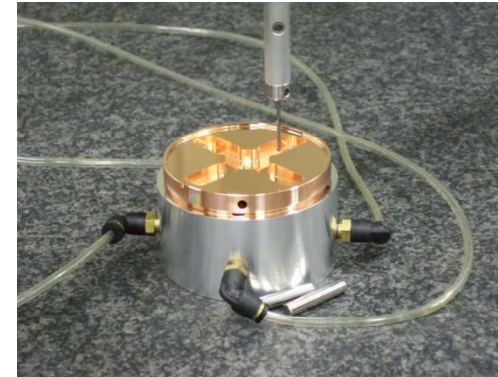
TD18_VG2.4_Disk Fabrication test



Cell #1



Cell #19



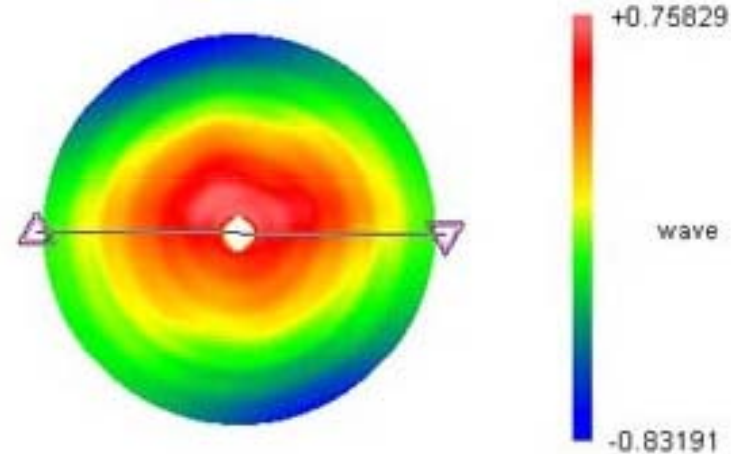
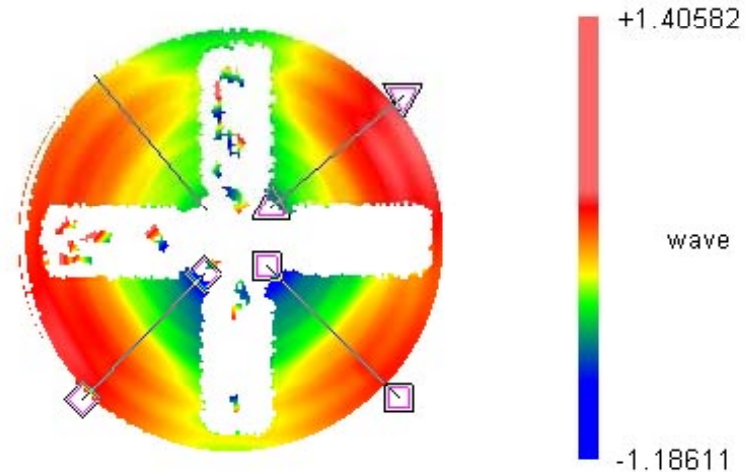
Most concerns are
Dimension
Flatness

Flatness

Flatness better than
1.5micron in free
position

We estimate that the
flatness becomes
better <1 micron
when pushed onto
the flat surface.

Flatness if OK.



We found recently the difficulty in dimension control

- Different measurement results between vendor and KEK about ~20microns!

Vendor suffers from big burrs at the top

The creation of burr itself should be suppressed!

→ improve finish turning. Study in progress.

If it is not realized by vendor, KEK should do final cut.

The re-scheduling become needed.

- Slanted wall for waveguide channel and cell wall by several microns / several mm depth. Too much!! We are under investigation of improvement.

- We wait for the confirmation of the reasonable precision It should be within several microns

- C10 and CD10 follow the fabrication of Disk-damp

Quad fabrication and test

- Present mission
 - Fabrication with all ball point milling
 - Assembly for high power realization
 - Non heat treated cavity in a vacuum vessel
- Discussions to be made
 - Feasibility for near future LC
 - Pros and cons in general
 - Precision alignment issue comes after high power

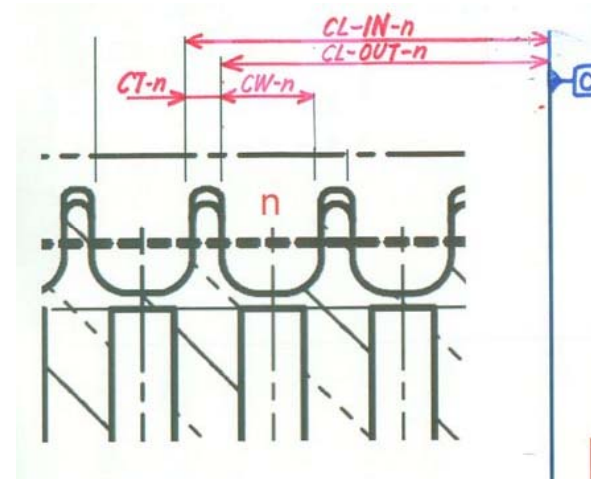
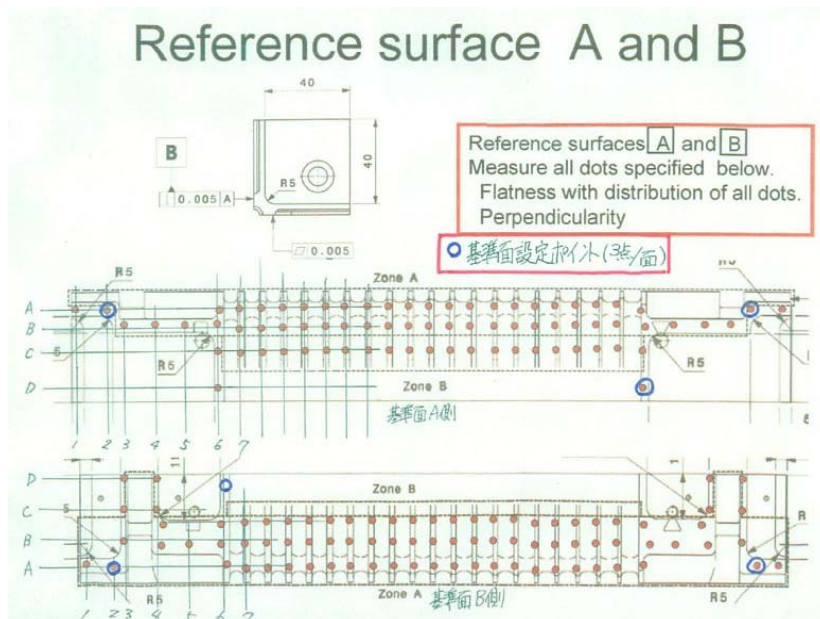
Status of four quadrants

- Brushed up the machining technique
 - Longitudinal: a few microns / 200mm
 - We think this controllability necessary to assure the precision of the overall 3D surface creation
 - Transverse direction: within \pm a few microns
- Now we decided to make the actual four quadrants
 - Four will be delivered to KEK by mid Nov.

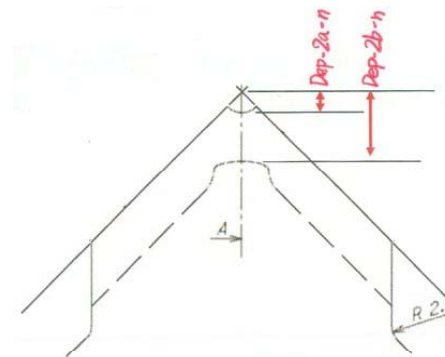
Dimensions to be confirmed

Longitudinal position

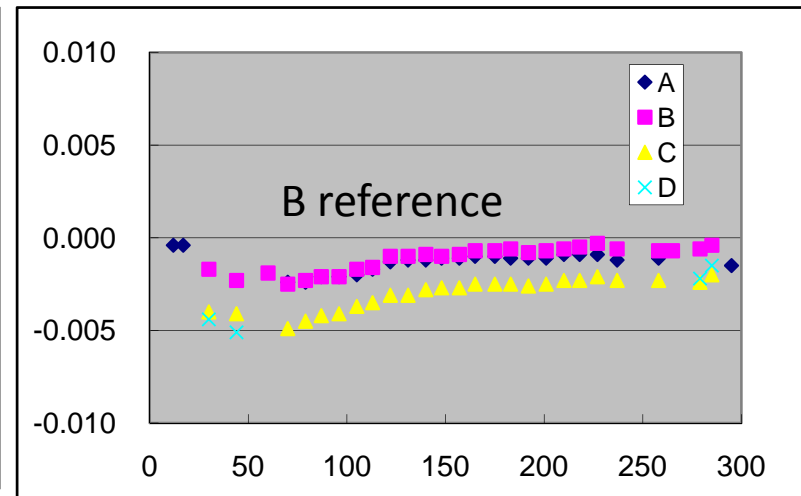
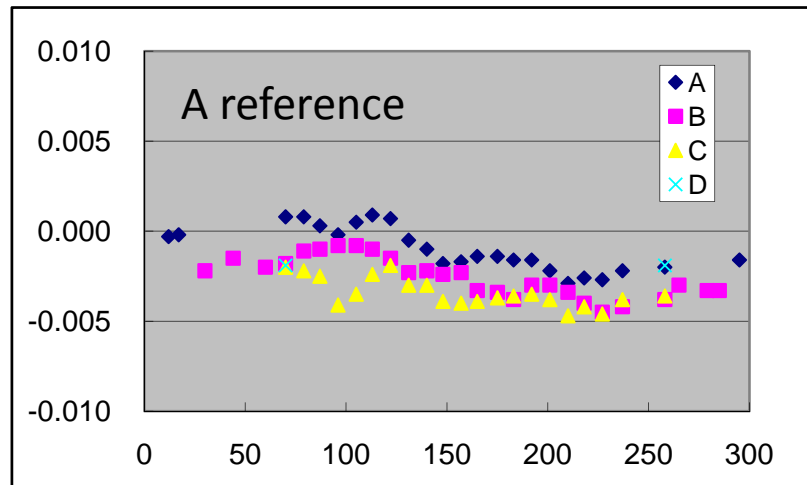
Flatness



Depth of cell surface (a, b)



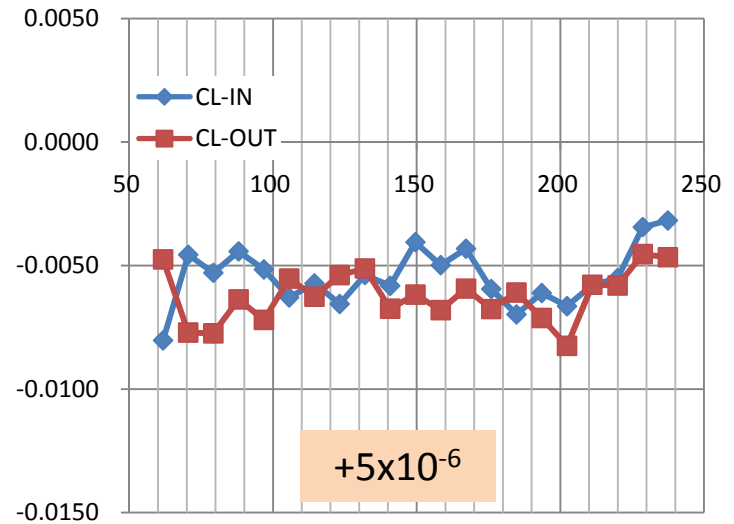
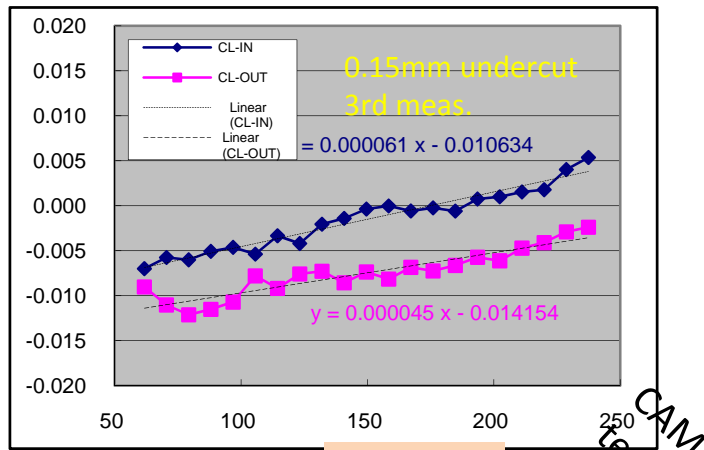
Reference surface flatness



A Flatness: 4 μm
B Flatness: 3 μm , Perpendicularity w.r.t. A: 4 μm
C Perpendicularity w.r.t. A+B: 2 μm

Measurement was performed by vendor.
KEK measurement is consistent.

Longitudinal dimension control



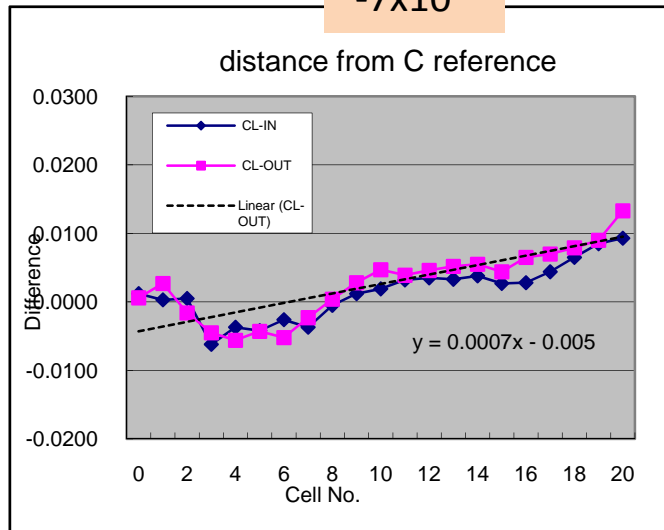
Machine tune up.



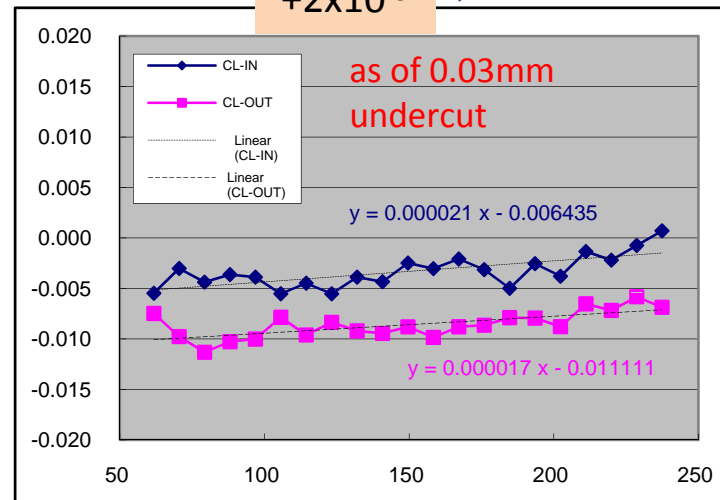
-7×10^{-4}

$+5 \times 10^{-5}$

CAM Temp. correction



$+2 \times 10^{-5}$



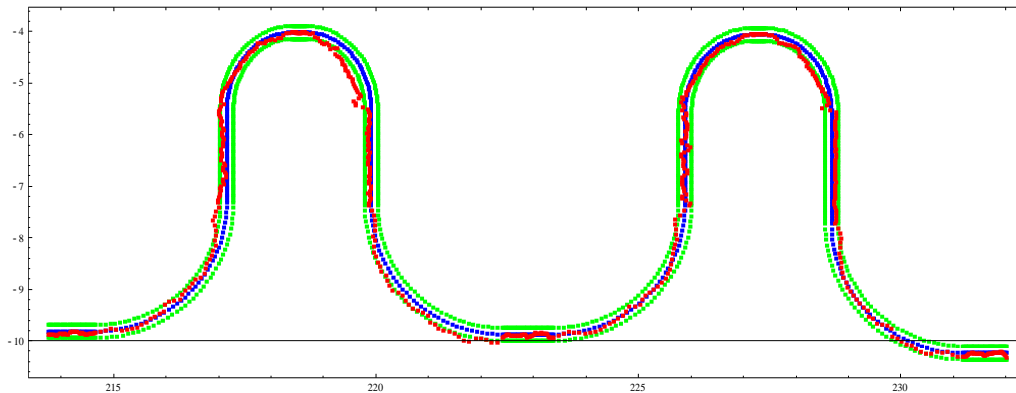
Reproducibility
 $\sim 4 \mu\text{m} / 200\text{mm}$

Profile of test cut quadrant Q1-0

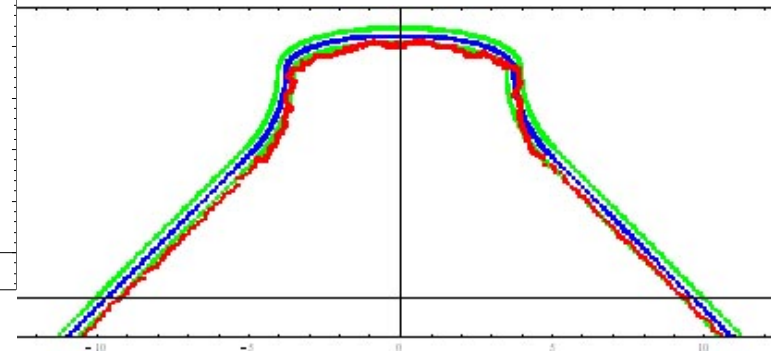
Measured w.r.t. A-B-C reference planes.

Green lines are ± 2.5 microns.

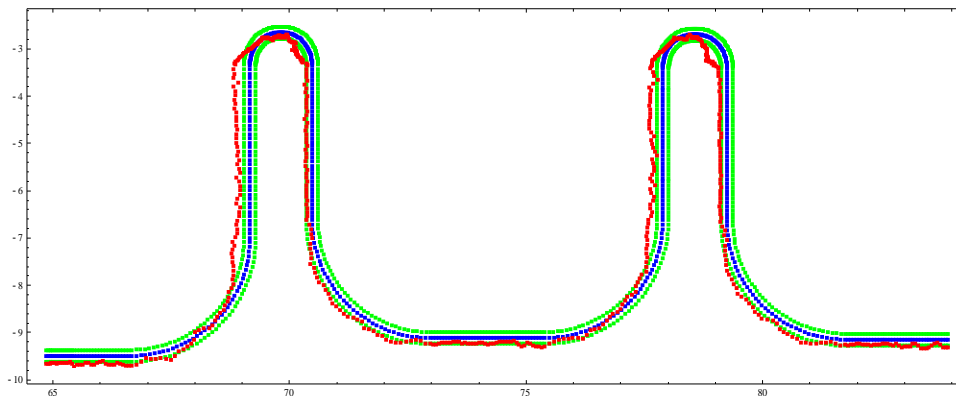
KUM data = NWDSQ7.csv



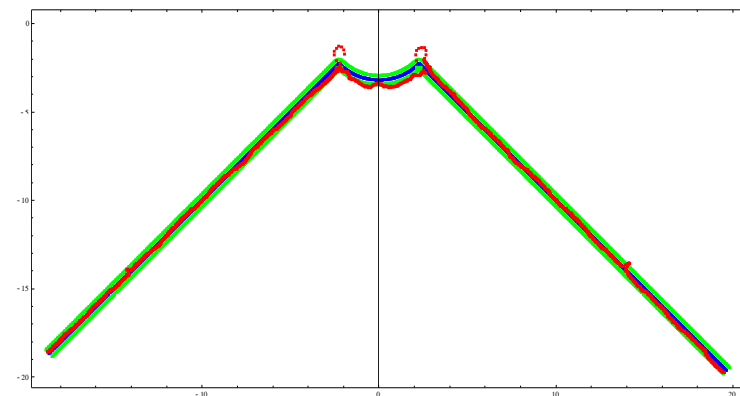
KUM data = NWDS13.csv



KUM data = NWDS10.csv



KUM data = NWDS17.csv



Milled surface view

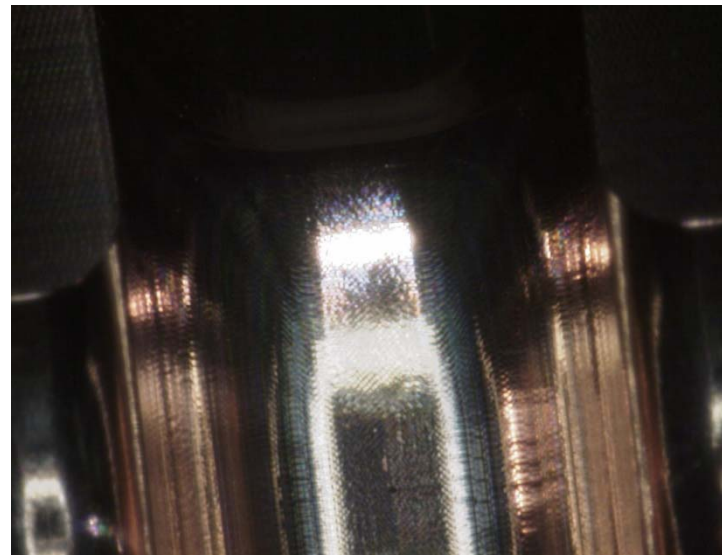
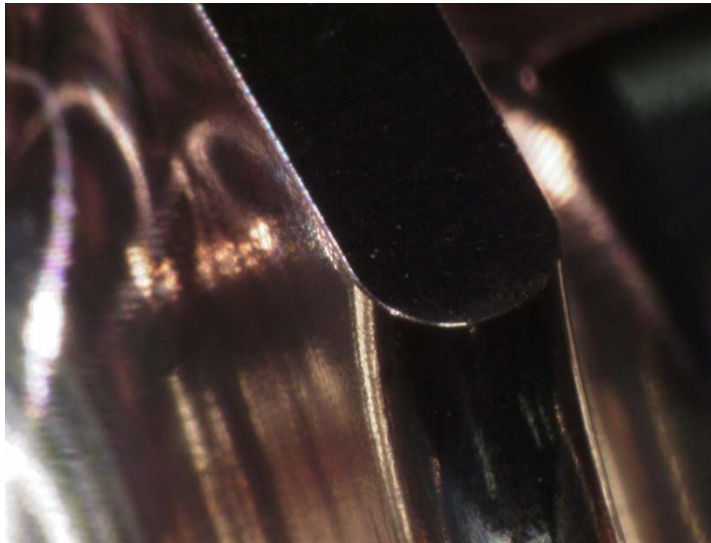


50 micron rounding

Reference plane formation by milling

Cavity wall formation

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Tuning sensitivity and requirement

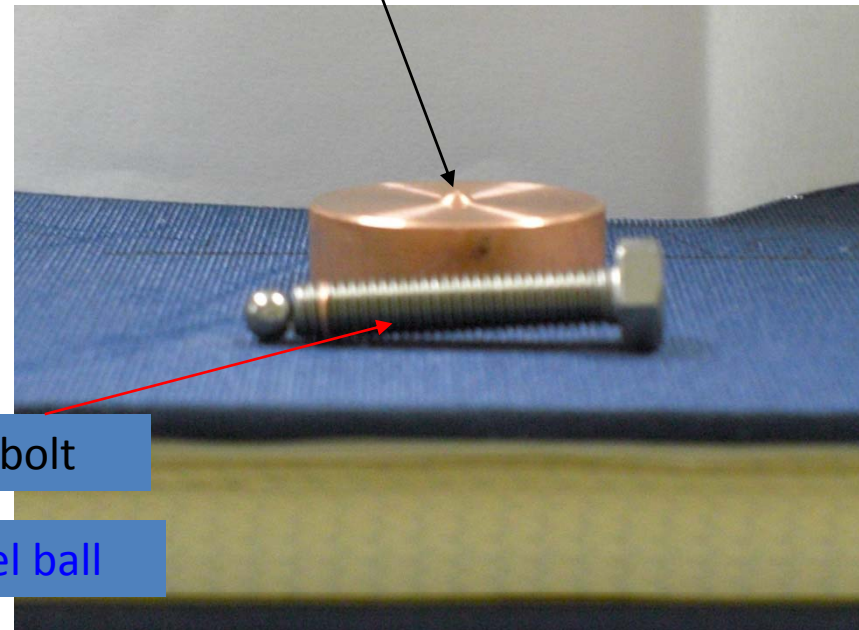
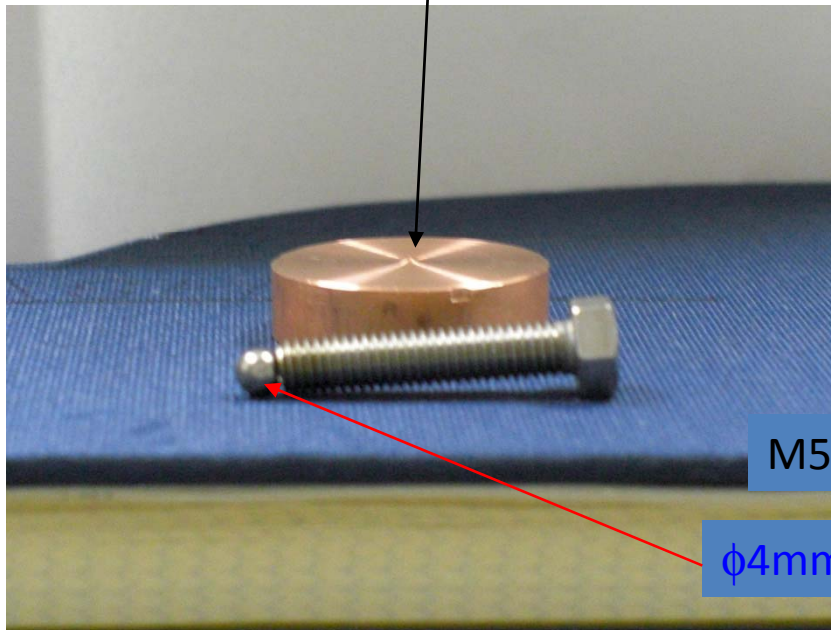
- Cavity sensitivity by Riccardo
 - $df/db = -1\text{MHz/micron}$
 - $df/da = +0.24\text{MHz/micron}$
 - $df/d\text{gap}$ (gap between quads) = $+0.37\text{MHz/micron}$
- Tuning sensitivity
 - Riccardo: $+10\text{MHz}/0.3\text{mm}$ -push, $-10\text{MHz}/0.4\text{mm}$ -push-back
 - Higo: cone, height h , base $r=4.2/2$:
 - $df/dh = +12\text{MHz/mm}$
- Tuning amount
 - Riccardo requirement form RF match: $\pm 5\text{MHz}$
 - Vendor potential $\sim \pm 5\mu\text{m} \rightarrow \pm 5\text{MHz}$
 - Required tuning amount $< \pm 10\text{MHz} \rightarrow 0.5\text{mm/hole}$
 - Fab. At 20C and operation at $30\text{C} \rightarrow -2\text{MHz}$
 - Temperature tuning capability $\pm 10\text{C} \rightarrow \pm 2\text{MHz}$

Rough test results of dimpling for rf tuning 081003 Y.Higashi

Dimpled height

0.43mm+/- 50 μ m

0.63mm+/- 50 μ m



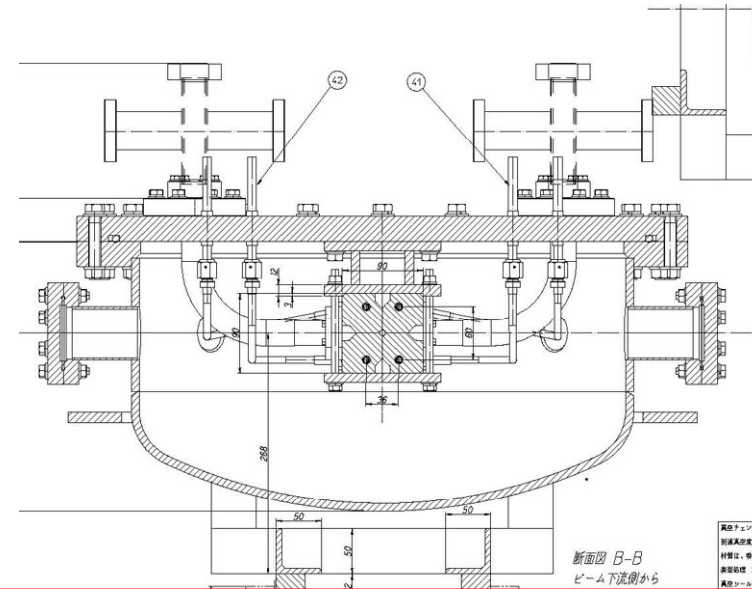
M5 SUS bolt

ϕ 4mm steel ball

Not big torque was applied -> standard torque for M5 bolt

@ Deterioration of flatness, straightness and twist of structure due to dimple tuning should be considered.

Vacuum chamber preparation



- Quads are assembled and fixed to upper big flange.
- CF114 flange equipped with waveguide flange feature.
- Adjustment of electric phase and position might be difficult.
 - We may introduce bellows to CF114?
 - Gaskets with different thicknesses are prepared for adjustment.
- VCR connector for copper cooling tube with EBW to quad body.
- Vacuum sealing by U-tight seal, similar to helicoflex but cheap.
- Chamber is EP finish. Baking or not??

Summary

- **Disk-undamp** fabrication #3, #4 in progress at SLAC.
- **Disk-damp** test cell inspected and some improvement was found necessary before actual fabrication all by vendor.
- **Quad** actual fabrication in in progress, and vacuum chamber fabrication also started.